

Product Summary (@ $T_A = +25^\circ\text{C}$)

V_{RRM} (V)	I_o (A)	$V_{F(MAX)}$ (V)	$I_{R(MAX)}$ (mA)
60	5	0.52	0.5

Applications

- SMPS
- AC-DC
- DC-DC Converter
- Freewheeling Diodes

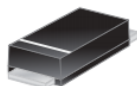
Features and Benefits

- Low Leakage Current
- Soft, Fast Switching Capability
- +150°C Operating Junction Temperature
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact@diodes.com) or your local Diodes representative.**

<https://www.diodes.com/quality/product-definitions/>

Mechanical Data

- Case: SMAF
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish.) Solderable per MIL-STD-202, Method 208 (E3)
- Polarity Indicator: Cathode Band
- Weight: 0.036 grams (Approximate)



SMAF

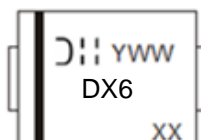


Device Symbol

Ordering Information (Note 4)

Part Number	Compliance	Package	Packaging
SDT5A60SAF-13	Commercial	SMAF	10,000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information (Note 5)


DX6 = Product Type Marking Code
 YWW = Manufacturers' Code Marking
 YWW = Date Code Marking
 Y = Last Digit of Year (ex: 1 for 2021)
 WW = Week Code (01 to 52)
 XX = Foundry and Assembly Site

Note: 5. Device has a cathode band (as shown) and may also have a cathode notch.

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	60	V
Working Peak Reverse Voltage	V _{RWM}	60	
DC Blocking Voltage	V _{RM}	60	
Average Rectified Output Current	I _O	5	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	50	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	51	°C/W
Thermal Resistance, Junction to Case (Note 6)	R _{θJC}	28	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Note: 6. Device mounted on FR-4 substrate, 1"×1", 2oz, single-sided, PC boards with 0.56"×0.73" copper pad. The heat generated must be less than the thermal conductivity from junction to case: dP_D/dT_J < 1/R_{θJC} or junction to ambient: dP_D/dT_J < 1/R_{θJA}.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V _F	—	0.46	0.52	V	I _F = 5.0A, T _J = +25°C
		—	0.39	0.45		I _F = 5.0A, T _J = +125°C
Leakage Current (Note 7)	I _R	—	—	0.5	mA	V _R = 60V, T _J = +25°C
		—	50	—		V _R = 60V, T _J = +125°C

Note: 7. Short duration pulse test used to minimize self-heating effect.

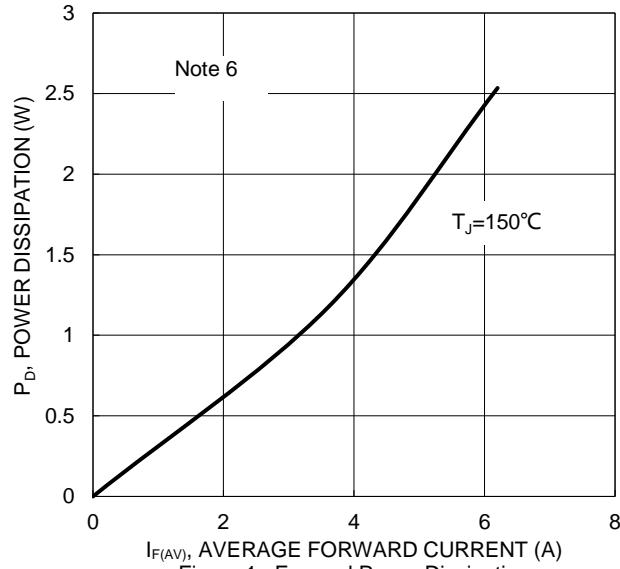


Figure 1. Forward Power Dissipation

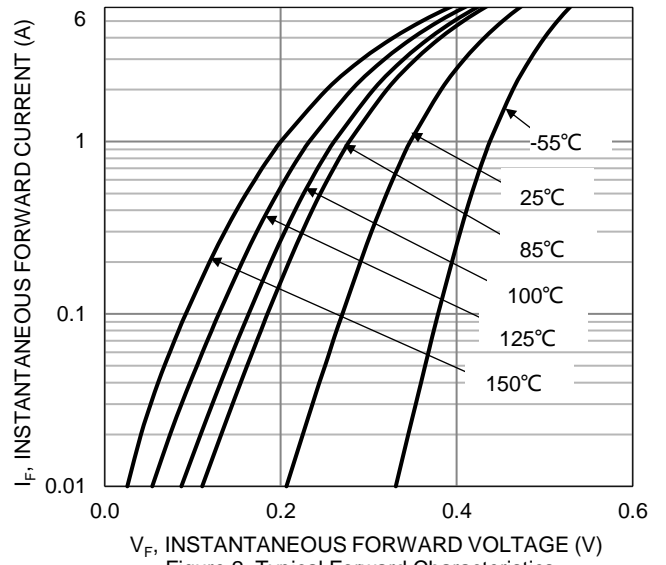


Figure 2. Typical Forward Characteristics

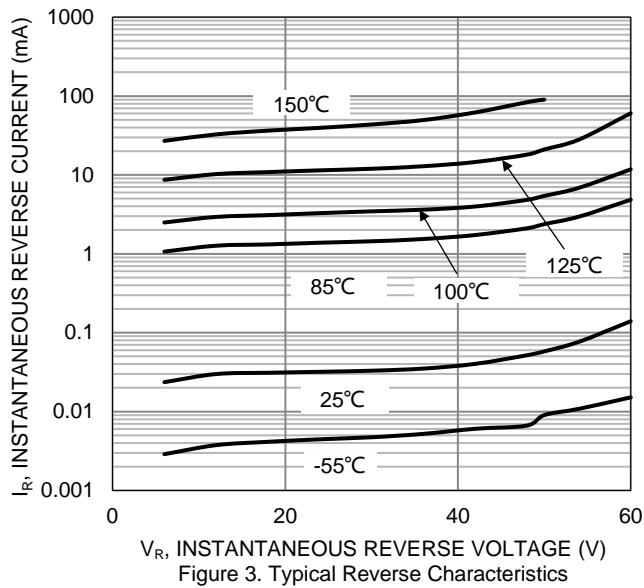


Figure 3. Typical Reverse Characteristics

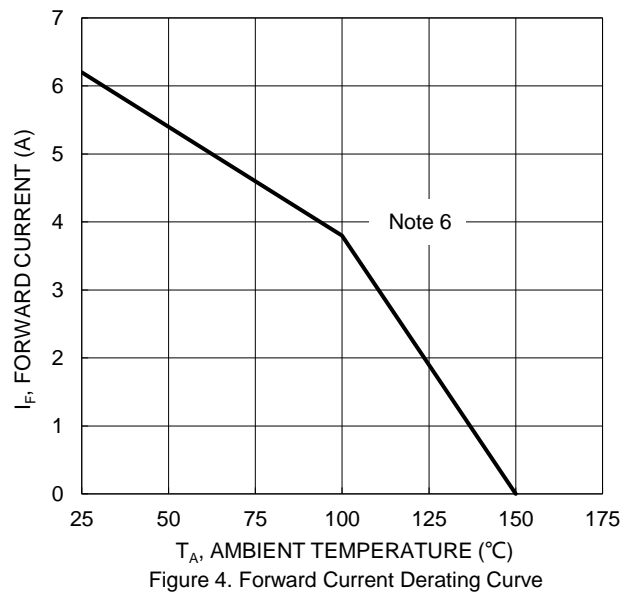
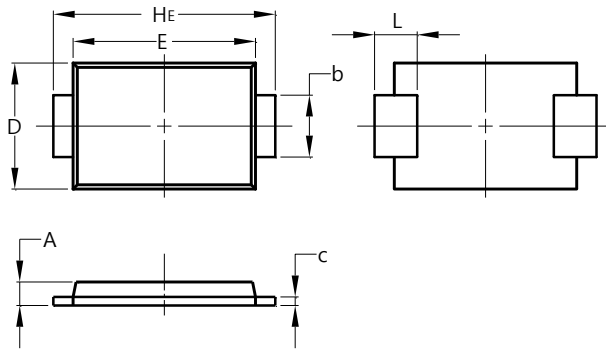


Figure 4. Forward Current Derating Curve

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SMAF

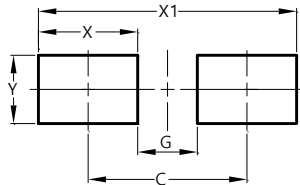


SMAF		
Dim	Min	Max
A	0.90	1.10
b	1.25	1.65
c	0.10	0.40
D	2.25	2.95
E	3.95	4.60
H _E	4.80	5.60
L	0.50	1.50
All Dimensions in mm		

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SMAF



Dimensions	Value (in mm)
C	4.00
G	1.50
X	2.50
X1	6.50
Y	1.70

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